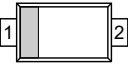
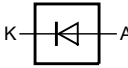


5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 CFP3 (SOD123W)	 006aab040
2	A	anode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PNS40010ER	CFP3	plastic, surface mounted package; 2 terminals; 2.6 mm x 1.7 mm x 1 mm body	SOD123W

7. Marking

Table 4. Marking codes

Type number	Marking code
PNS40010ER	EH

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage			-	400	V
V_R	reverse voltage			-	400	V
V_{RMS}	RMS voltage			-	280	V
I_F	forward current	$T_{sp} \leq 160\text{ }^{\circ}\text{C}$		-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 115\text{ }^{\circ}\text{C}$	[1]	-	1	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 170\text{ }^{\circ}\text{C}$		-	1	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; square wave		-	32	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[2]	-	750	mW
			[3]	-	1.3	W
			[1]	-	2.3	W
T_j	junction temperature			-	175	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	175	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	175	$^{\circ}\text{C}$

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

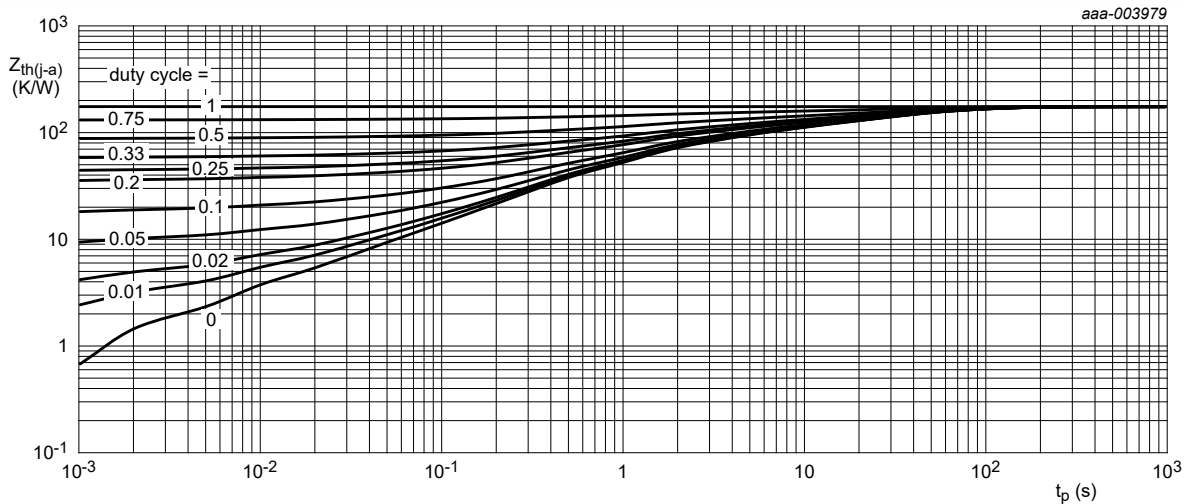
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	200	K/W
			[2]	-	-	115	K/W
			[3]	-	-	65	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	15	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

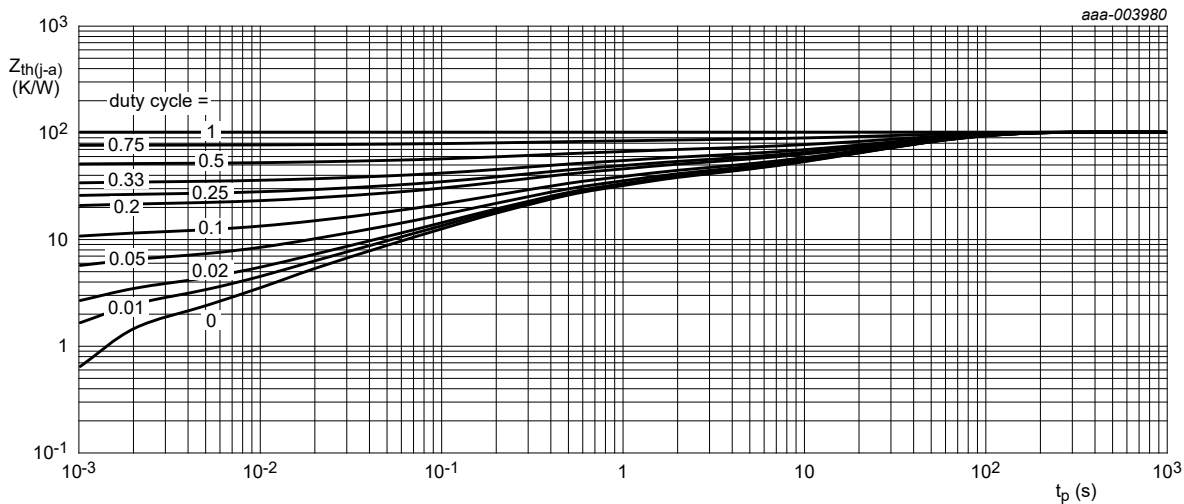
[3] Device mounted on an FR4 PCB, Al_2O_3 , standard footprint.

[4] Soldering point of cathode tab.



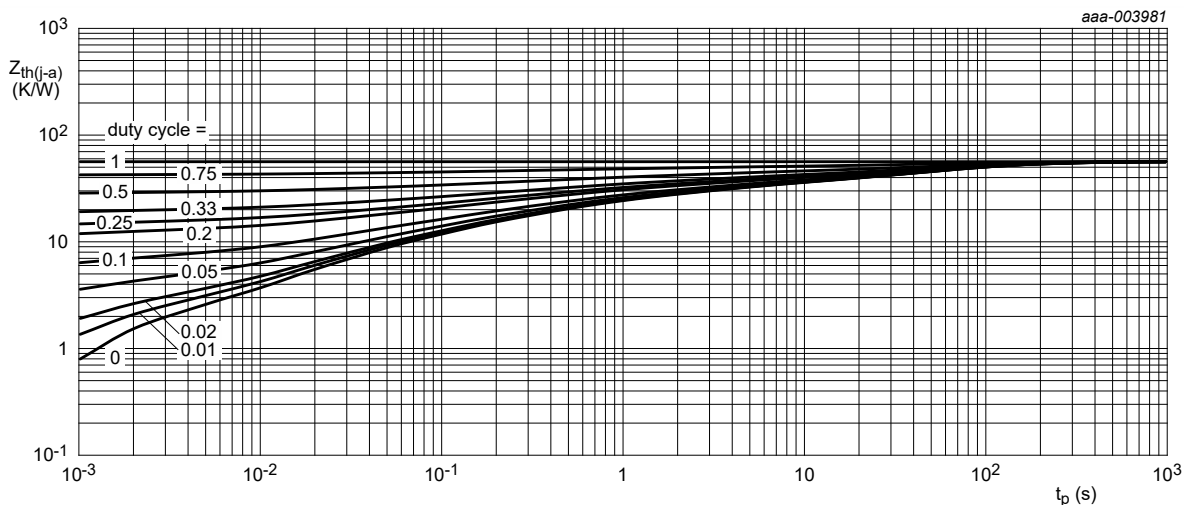
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



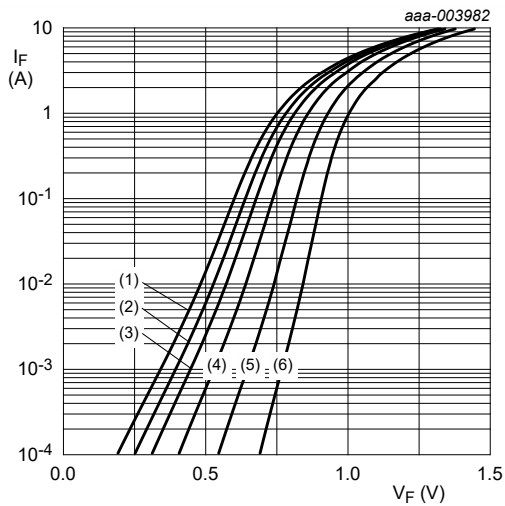
Ceramic PCB, Al₂O₃, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

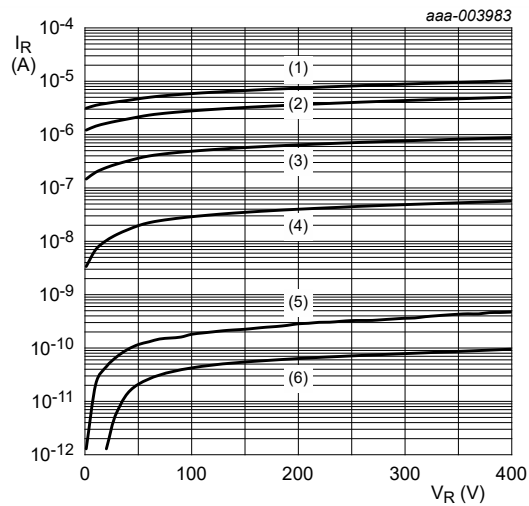
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.5 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	0.89	1.05	V
		$I_F = 0.7 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	0.91	1.07	V
		$I_F = 1 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	0.93	1.1	V
		$I_F = 0.5 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 125 \text{ }^\circ\text{C}$	-	0.76	0.92	V
		$I_F = 0.7 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 125 \text{ }^\circ\text{C}$	-	0.78	0.95	V
		$I_F = 1 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 125 \text{ }^\circ\text{C}$	-	0.81	0.98	V
		$I_F = 1 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = -40 \text{ }^\circ\text{C}$	-	1.01	1.18	V
		$I_F = 1 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 150 \text{ }^\circ\text{C}$	-	0.78	0.95	V
		$I_F = 1 \text{ A}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 175 \text{ }^\circ\text{C}$	-	0.75	0.92	V
I_R	reverse current	$V_R = 400 \text{ V}$; $T_j = -40 \text{ }^\circ\text{C}$	-	0.1	10	nA
		$V_R = 400 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	0.001	1	μA
		$V_R = 400 \text{ V}$; $T_j = 125 \text{ }^\circ\text{C}$	-	1	50	μA
		$V_R = 400 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$	-	5	250	μA
		$V_R = 400 \text{ V}$; $T_j = 175 \text{ }^\circ\text{C}$	-	10	500	μA
C_d	diode capacitance	$V_R = 4 \text{ V}$; $f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	8	20	pF
t_{rr}	reverse recovery time	$I_F = 0.5 \text{ A}$; $I_R = 1 \text{ A}$; $I_{R(\text{meas})} = 0.25 \text{ A}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	0.8	1.8	μs



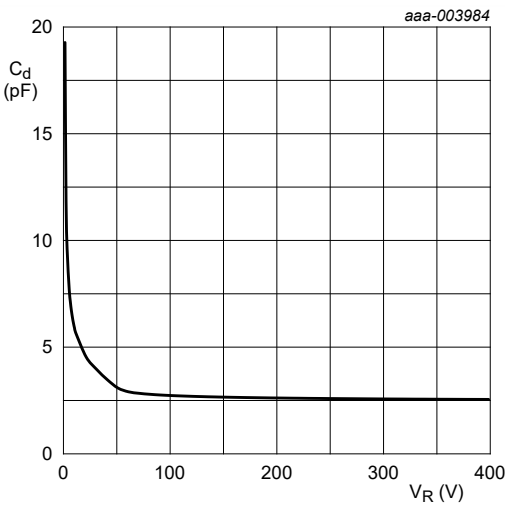
- (1) $T_j = 175^\circ\text{C}$
- (2) $T_j = 150^\circ\text{C}$
- (3) $T_j = 125^\circ\text{C}$
- (4) $T_j = 85^\circ\text{C}$
- (5) $T_j = 25^\circ\text{C}$
- (6) $T_j = -40^\circ\text{C}$

Fig. 4. Forward current as a function of forward voltage; typical values



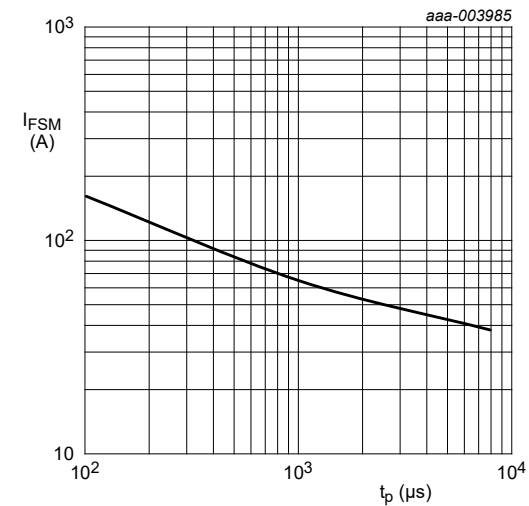
- (1) $T_j = 175^\circ\text{C}$
- (2) $T_j = 150^\circ\text{C}$
- (3) $T_j = 125^\circ\text{C}$
- (4) $T_j = 85^\circ\text{C}$
- (5) $T_j = 25^\circ\text{C}$
- (6) $T_j = -40^\circ\text{C}$

Fig. 5. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$; $T_{\text{amb}} = 25^\circ\text{C}$

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



$T_{\text{amb}} = 25^\circ\text{C}$

Fig. 7. Non-repetitive peak forward current as a function of pulse duration; typical values

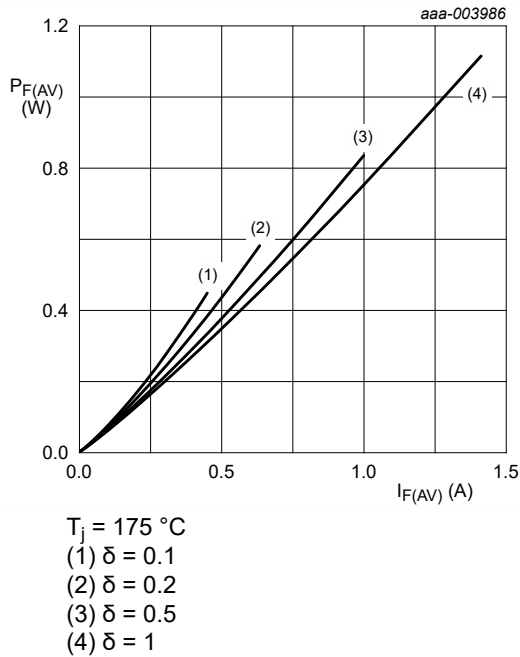


Fig. 8. Average forward power dissipation as a function of average forward current; typical values

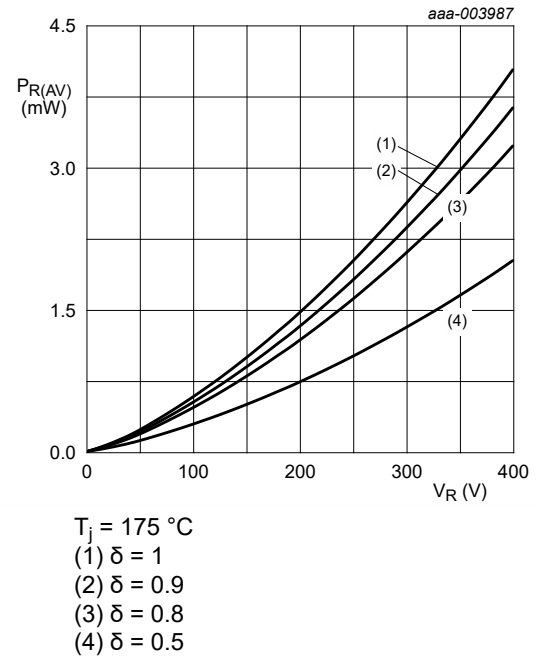


Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

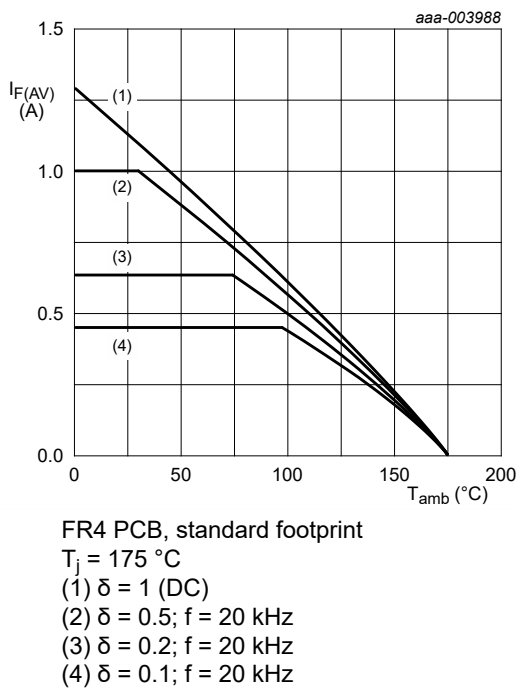


Fig. 10. Average forward current as a function of ambient temperature; typical values

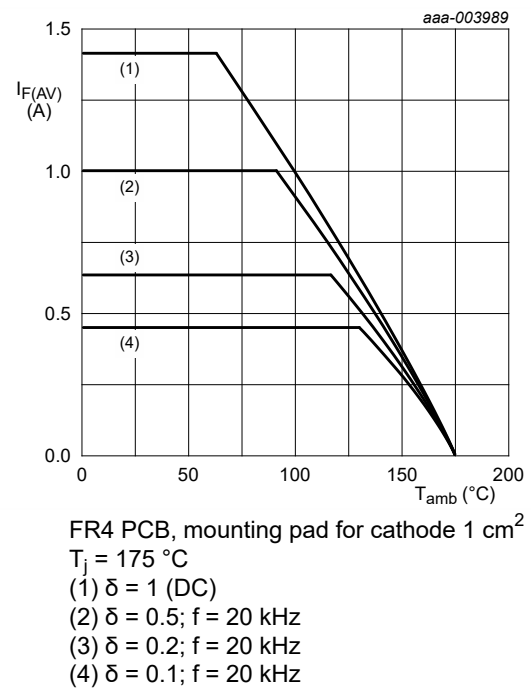
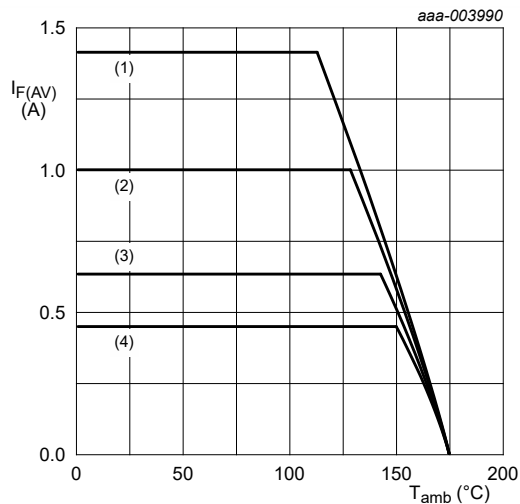
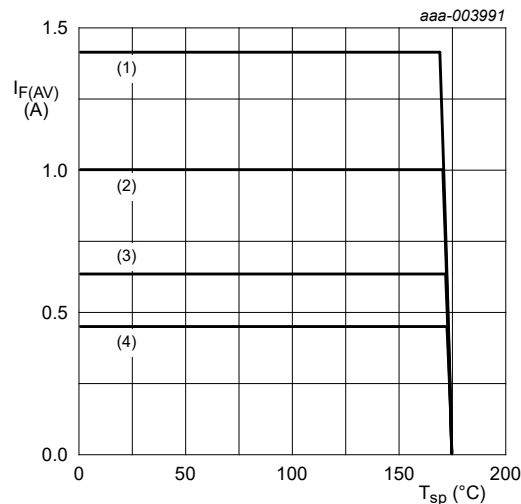


Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 175\text{ °C}$
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20\text{ kHz}$
(3) $\delta = 0.2$; $f = 20\text{ kHz}$
(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 175\text{ °C}$
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20\text{ kHz}$
(3) $\delta = 0.2$; $f = 20\text{ kHz}$
(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 13. Average forward current as a function of solder point temperature; typical values

11. Test information

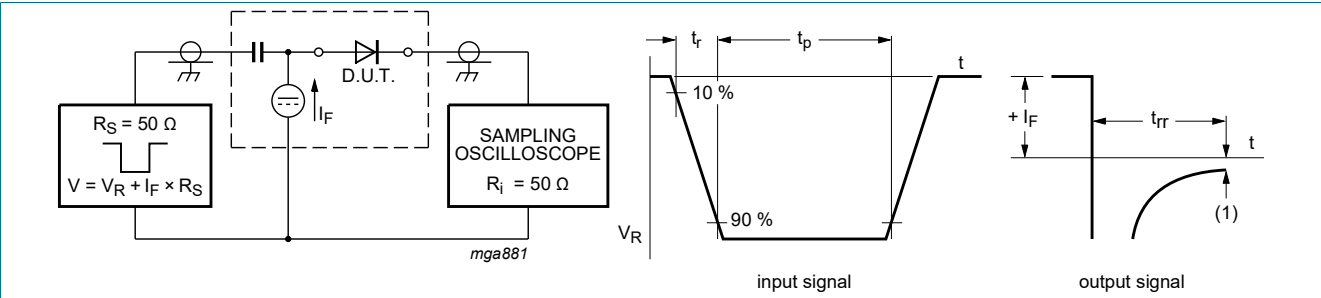


Fig. 14. Reverse recovery time: test circuit and waveforms

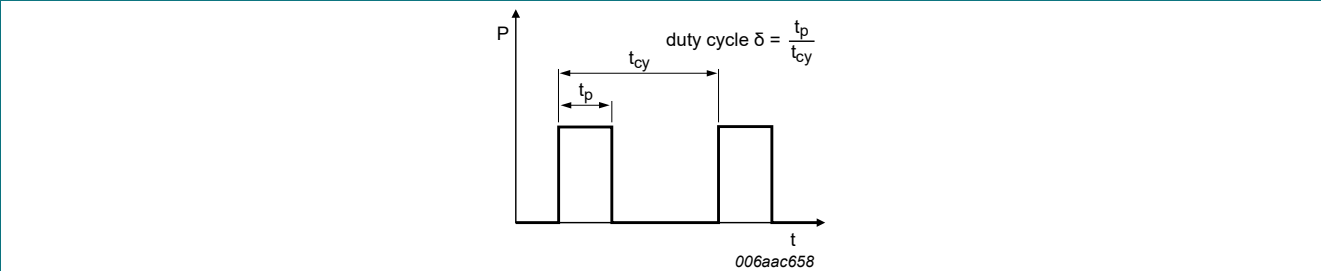


Fig. 15. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:
 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

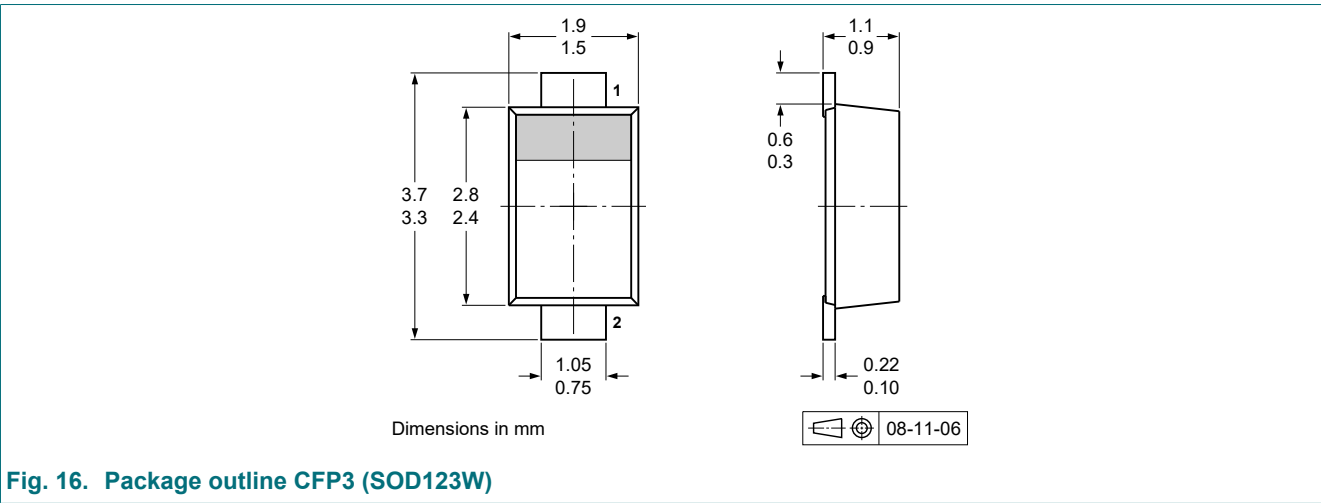
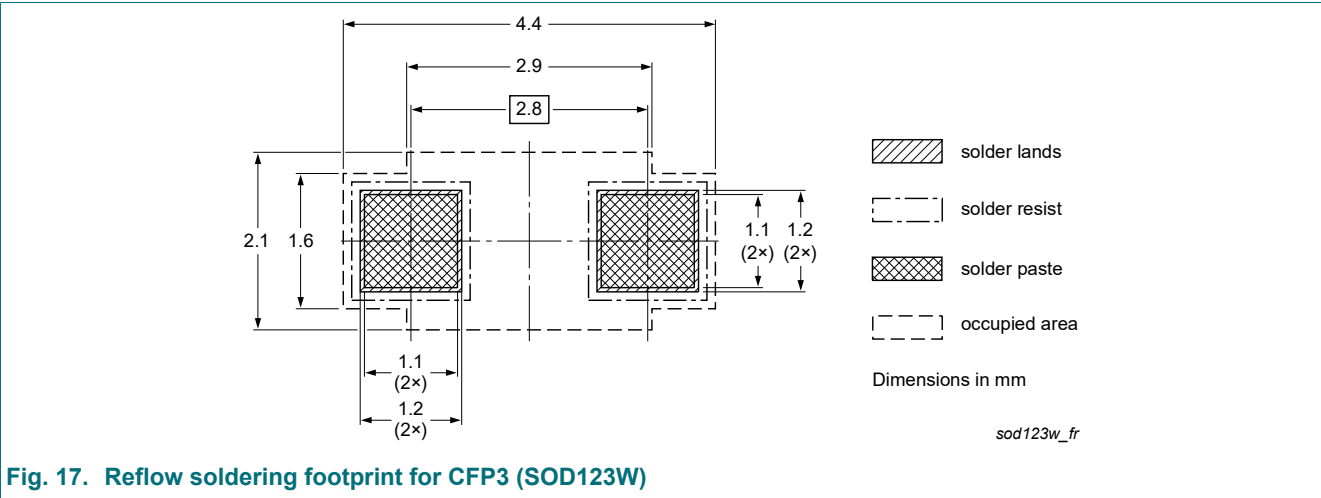


Fig. 16. Package outline CFP3 (SOD123W)

13. Soldering



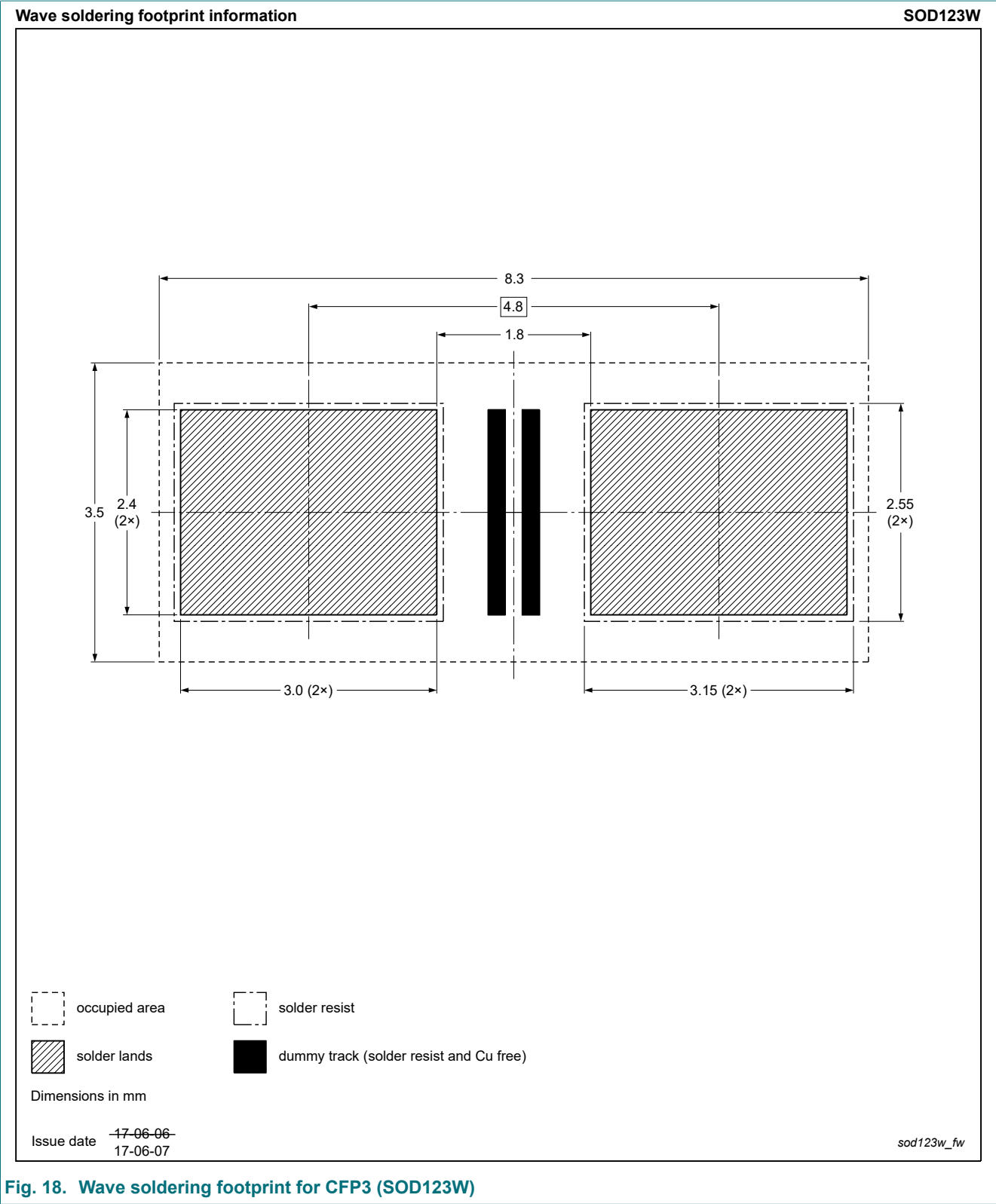


Fig. 18. Wave soldering footprint for CFP3 (SOD123W)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PNS40010ER v.4	20190819	Product data sheet	-	PNS40010ER v.3
Modifications:	• Category changed from PN-rectifier to recovery rectifier			
PNS40010ER v.3	20180822	Product data sheet	-	PNS40010ER v.2
PNS40010ER v.2	20120821	Product data sheet	-	PNS40010ER v.1
PNS40010ER v.1	20120615	Preliminary data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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